



SOT404

plastic single-ended surface-mounted package (D2PAK); 3 terminals (one lead cropped); 2.54 mm pitch; 11 mm x 10 mm x 4.3 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	11 x 10 x 4.3
Terminal position code	S (single)
Package type descriptive code	D2PAK
Package outline version code	SOT404
Manufacturer package code	SOT404
Package type industry code	D2PAK
Package outline version description	plastic single-ended surface-mounted package (D2PAK); 3 terminals (one lead cropped); 2.54 mm pitch; 11 mm x 10 mm x 4.3 mm body
Package style descriptive code	SMS (surface-mounted single in-line)
Package body material type	P
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	S (surface mount)
Generic mounting and soldering information	SC18_2004_CHAPTER_4_3
Reflow soldering footprint	SOT404-REFLOW
Package life cycle status	REL
Major version date	18-9-2008
Minor version date	6-9-2016
Security status	COMPANY PUBLIC
Modified date	19-11-2012
Issue date	25-2-2013
Web publication date	28-11-2012
Initial web publication date	1-3-2011
Customer specific indicator	N
Maturity	Product

Table 1. Package summary

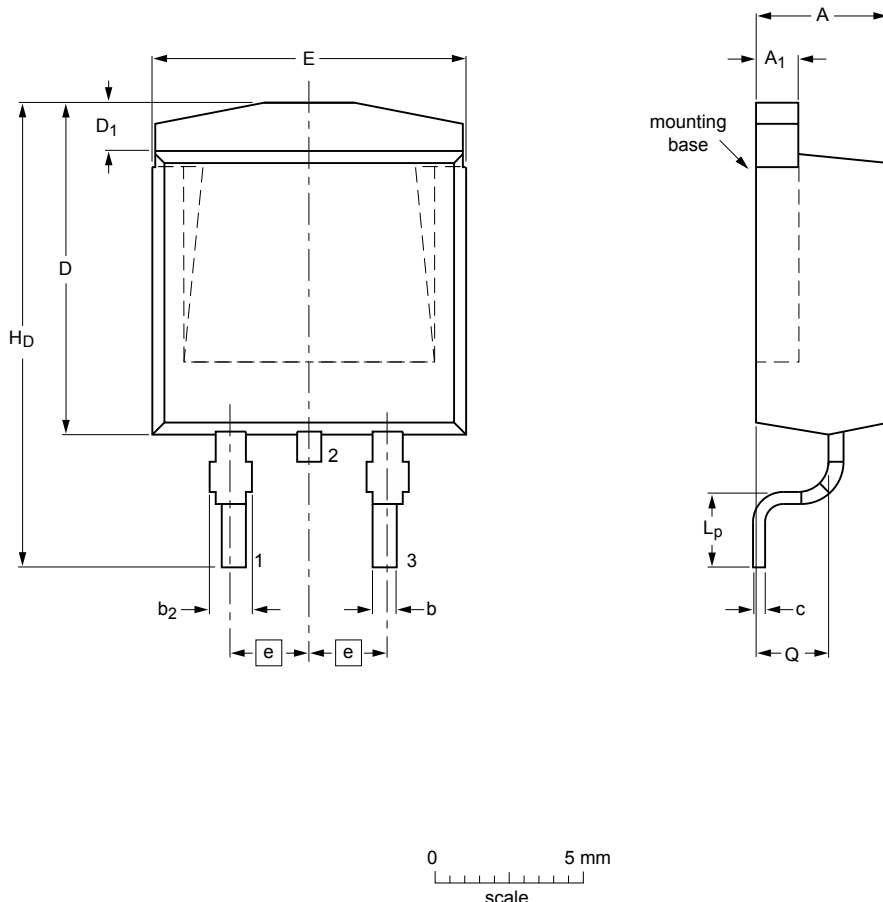
Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	4.1	-	4.3	4.5	mm
D	package length	-	-	11	11	mm
E	package width	9.7	-	10	10.3	mm
e	nominal pitch	-	-	2.54	-	mm
n ₂	actual quantity of termination	-	-	3	-	



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2. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) SOT404



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₂	c	D	D ₁	E	e	H _D	L _p	Q
max	4.5	1.40	0.85	1.45	0.64	11	1.6	10.3		15.8	2.9	2.6
nom									2.54			
min	4.1	1.27	0.60	1.05	0.46		1.2	9.7		14.8	2.1	2.2

sot404_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT404					-06-03-16- 13-02-25

Fig. 1. Package outline D2PAK (SOT404)

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3. Soldering

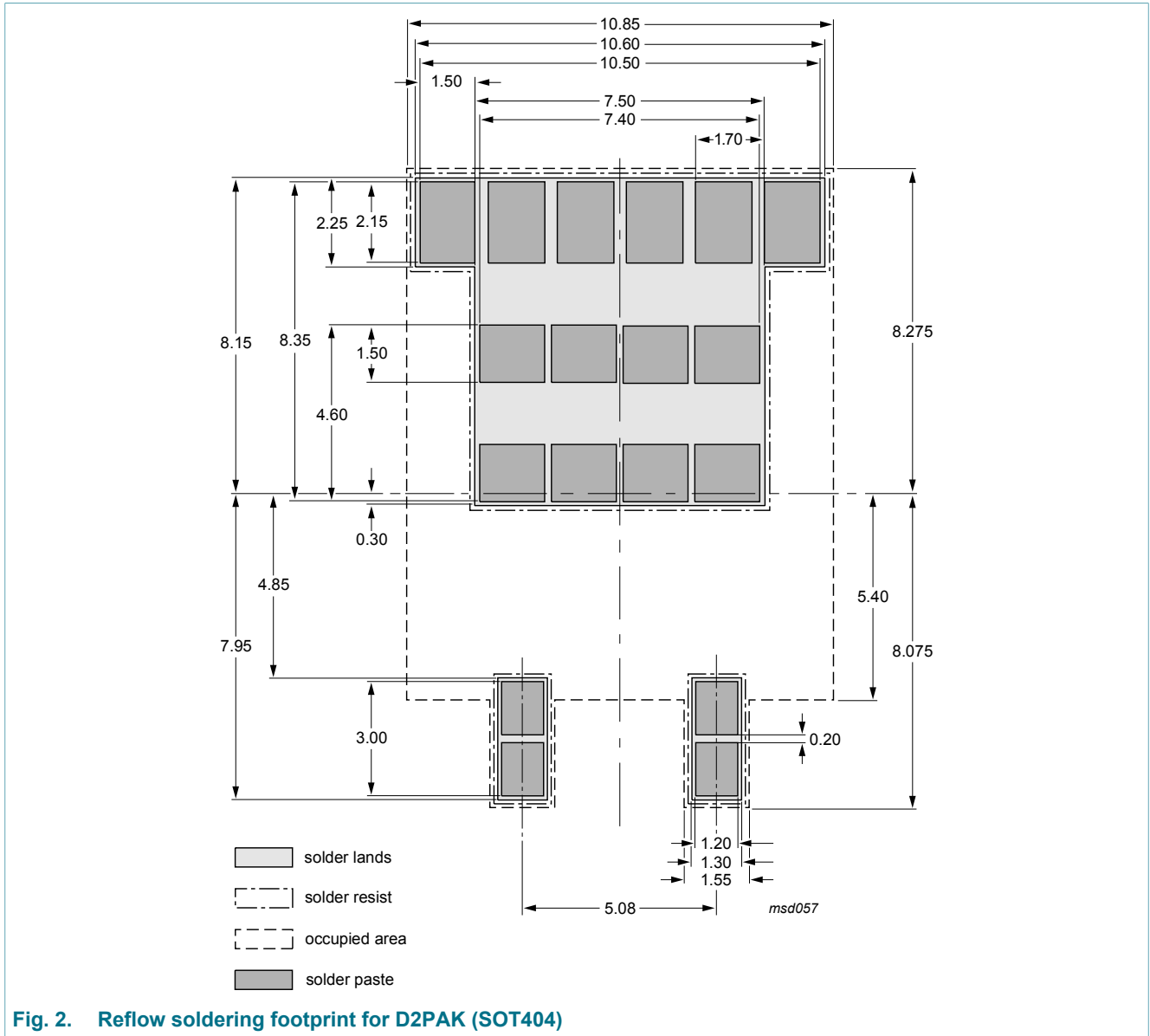


Fig. 2. Reflow soldering footprint for D2PAK (SOT404)

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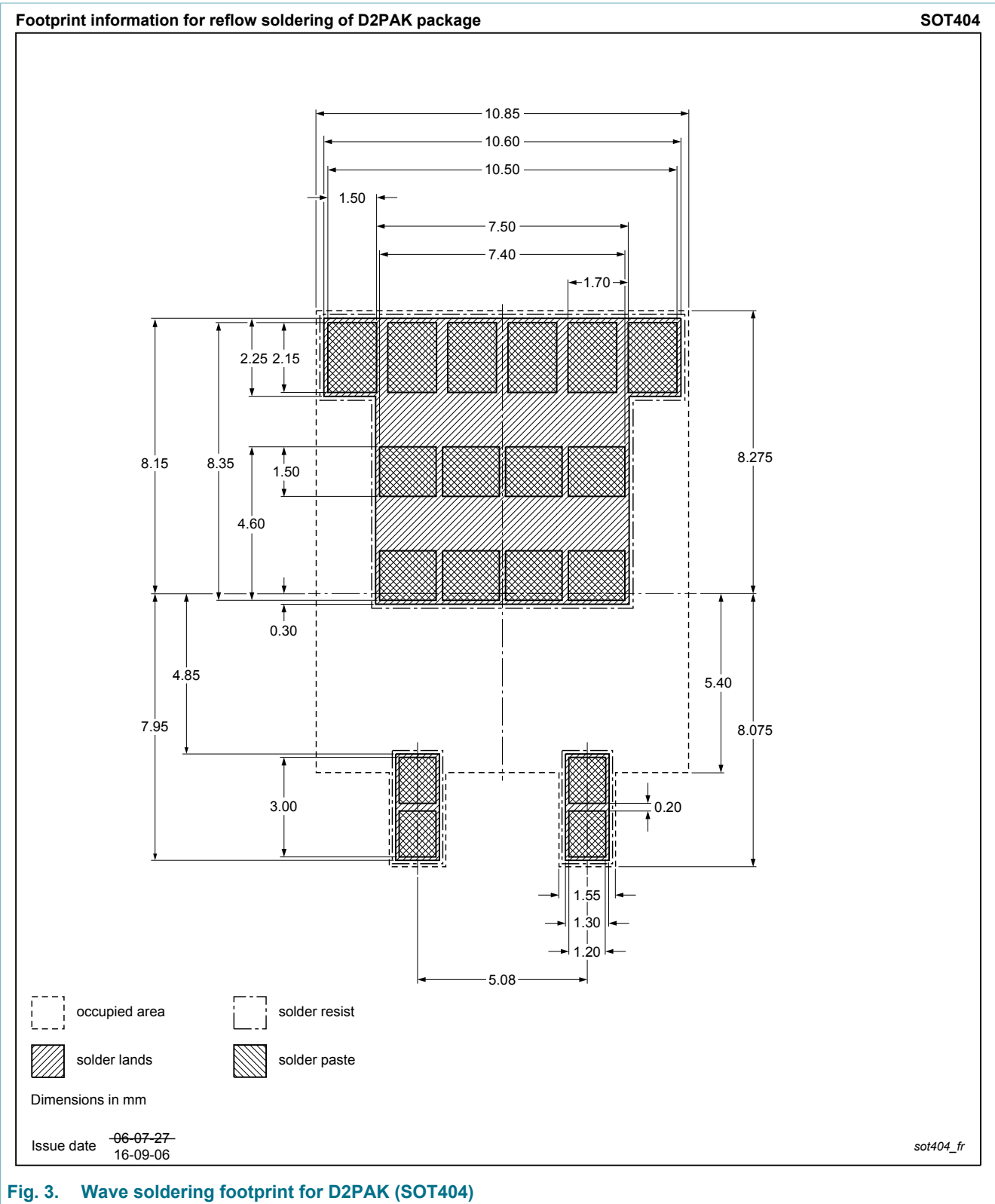


Fig. 3. Wave soldering footprint for D2PAK (SOT404)

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4. Legal information

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